

SOT1840-3

FBGA621, fine-pitch ball grid array package; 621 terminals,
0.65 mm pitch, 17 mm x 17 mm x 2.03 mm body

17 October 2018

Package information

1 Package summary

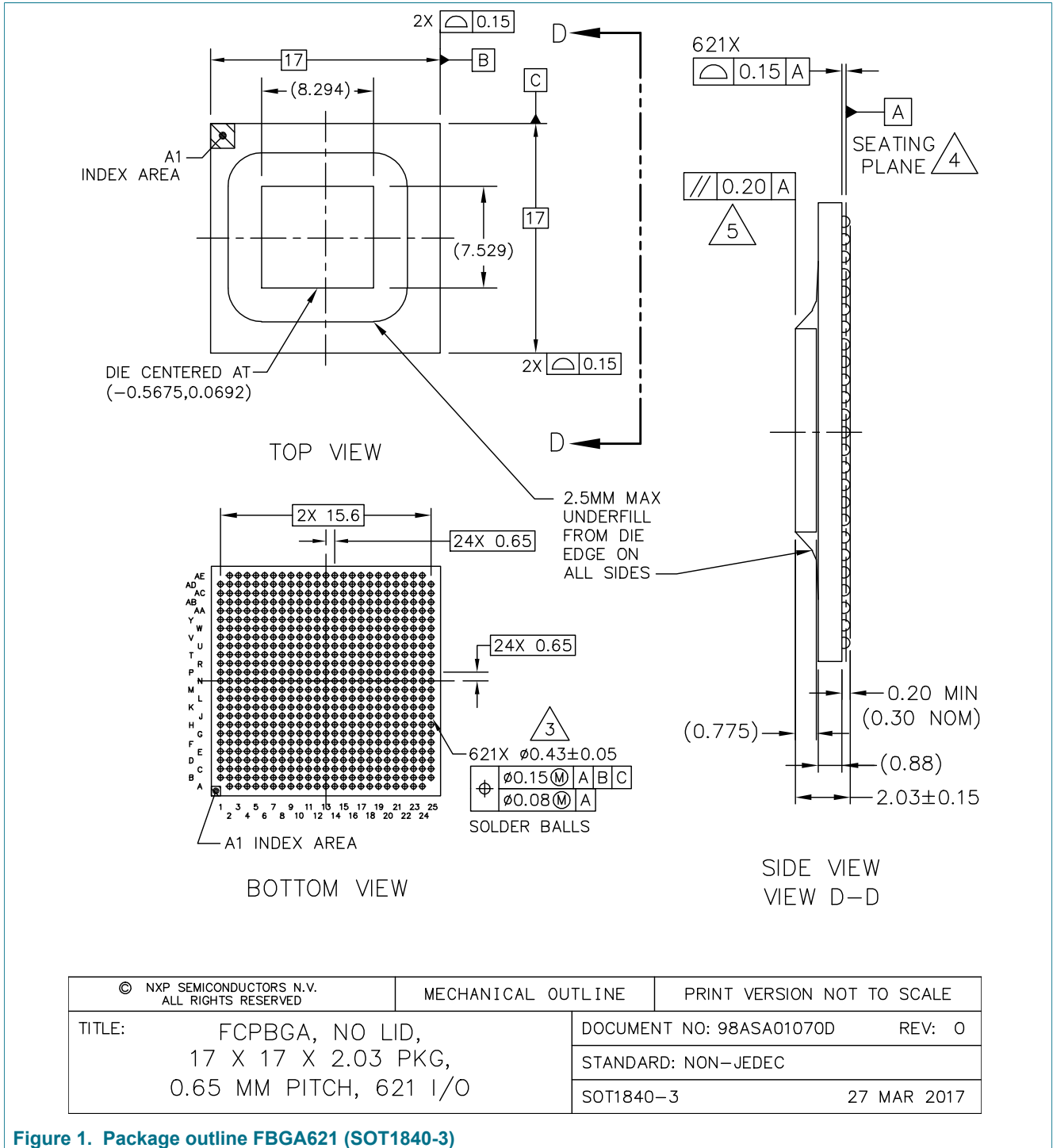
Terminal position code	B (bottom)
Package type descriptive code	FBGA621
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	27-03-2017
Manufacturer package code	98ASA01070D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	2.03	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	621	-	



2 Package outline



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TITLE: FCPBGA, NO LID, 17 X 17 X 2.03 PKG, 0.65 MM PITCH, 621 I/O	DOCUMENT NO: 98ASA01070D	REV: 0
	STANDARD: NON-JEDEC	
	SOT1840-3	27 MAR 2017

Figure 1. Package outline FBGA621 (SOT1840-3)

FBGA621, fine-pitch ball grid array package; 621 terminals, 0.65 mm pitch, 17 mm x 17 mm x 2.03 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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Figure 2. Package outline note FBGA621 (SOT1840-3)

3 Legal information

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